

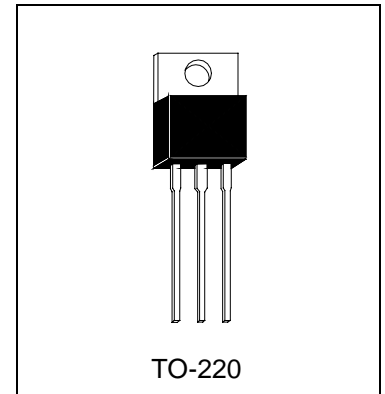


# HMJE2955T

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HMJE2955T is designed for general purpose of amplifier and switching applications.



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature ..... 150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (Tc=25°C) ..... 75 W
  - Total Power Dissipation (Ta=25°C) ..... 0.6 W
- Maximum Voltages and Currents
  - BVCBO Collector to Base Voltage ..... -70 V
  - BVCEO Collector to Emitter Voltage ..... -60 V
  - BVEBO Emitter to Base Voltage ..... -5 V
  - IC Collector Current ..... -10 A
  - IB Base Current ..... -6 A

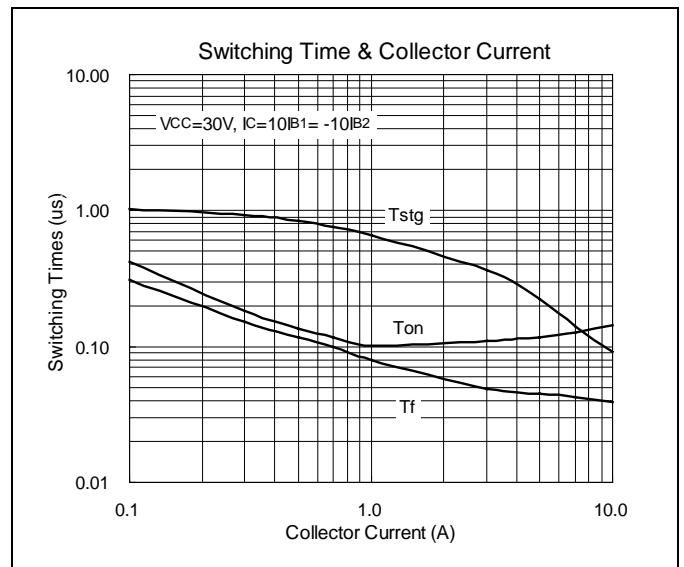
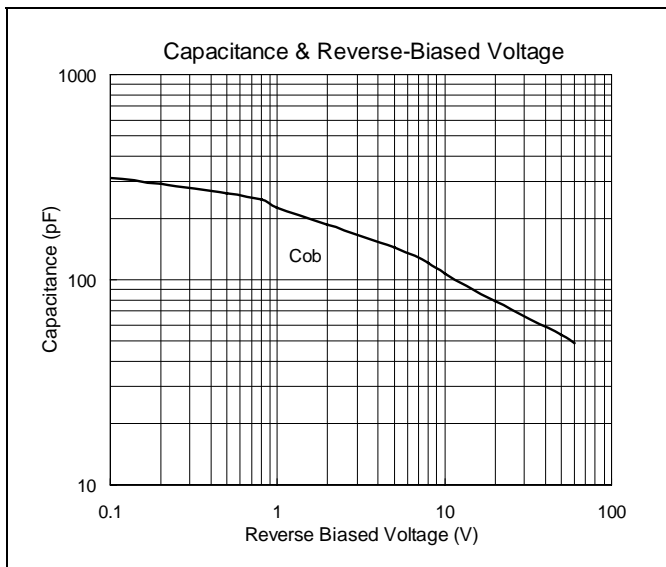
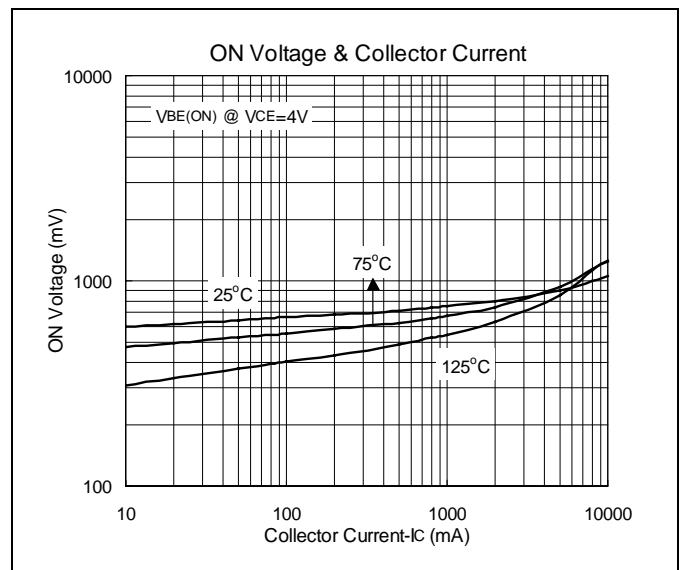
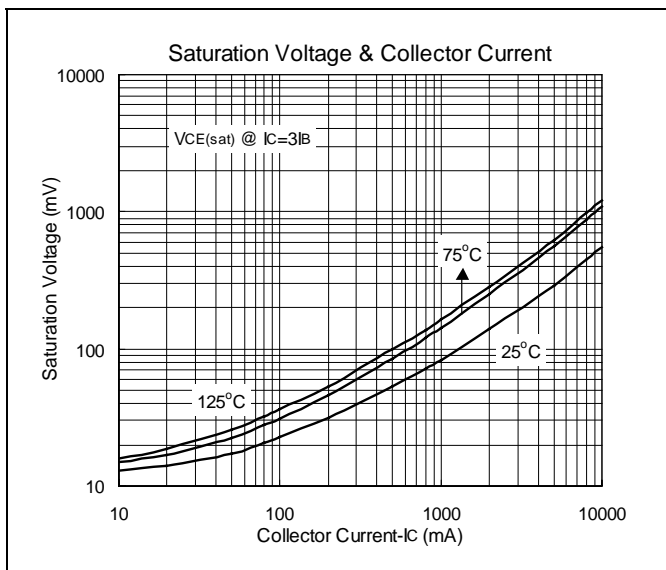
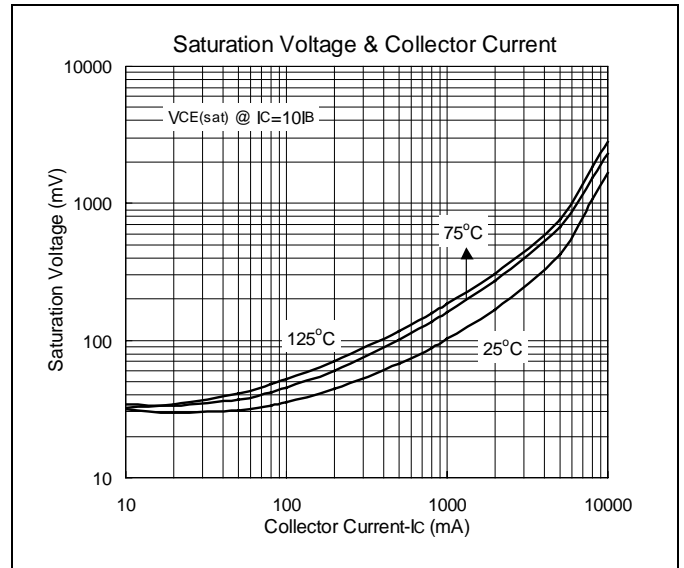
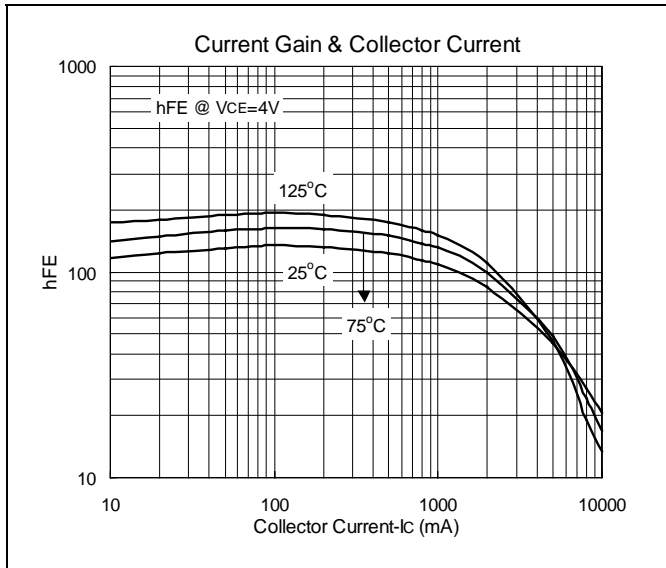
## Characteristics (Ta=25°C)

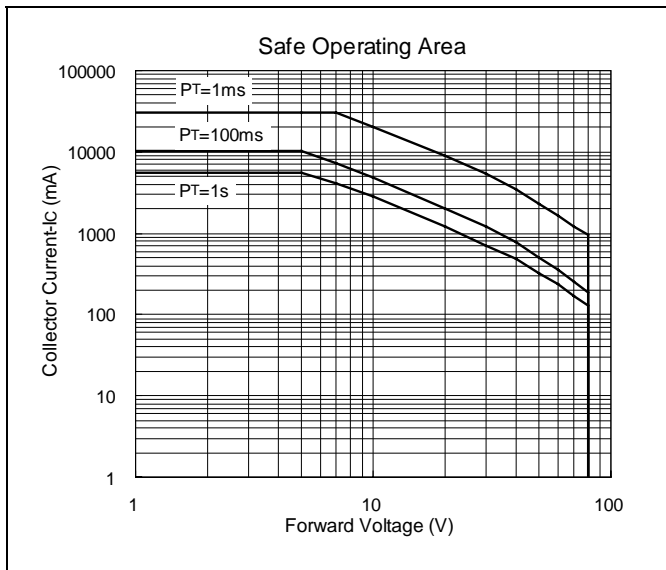
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-70	-	-	V	IC=-10mA, IE=0
BVCEO	-60	-	-	V	IC=-200mA, IB=0
BVEBO	-5	-	-	V	IE=-1mA, IC=0
ICBO	-	-	-1	mA	VCB=-70V, IE=0
ICEX	-	-	-1	mA	VCE=-70V, VEB(off)=-1.5V
ICEO	-	-	-700	uA	VCE=-30V, IB=0
IEBO	-	-	-5	mA	VEB=-5V, IC=0
*VCE(sat)1	-	-	-1.1	V	IC=-4A, IB=-400mA
*VCE(sat)2	-	-	-8	V	IC=-10A, IB=-3.3A
*VBE(on)	-	-	-1.8	V	IC=-4A, VCE=-4V
*hFE1	20	-	100		IC=-4A, VCE=-4V
*hFE2	5	-	-		IC=-10A, VCE=-4V
fT	2	-	-	MHz	VCE=-10V, IC=-500mA, f=0.5MHz

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



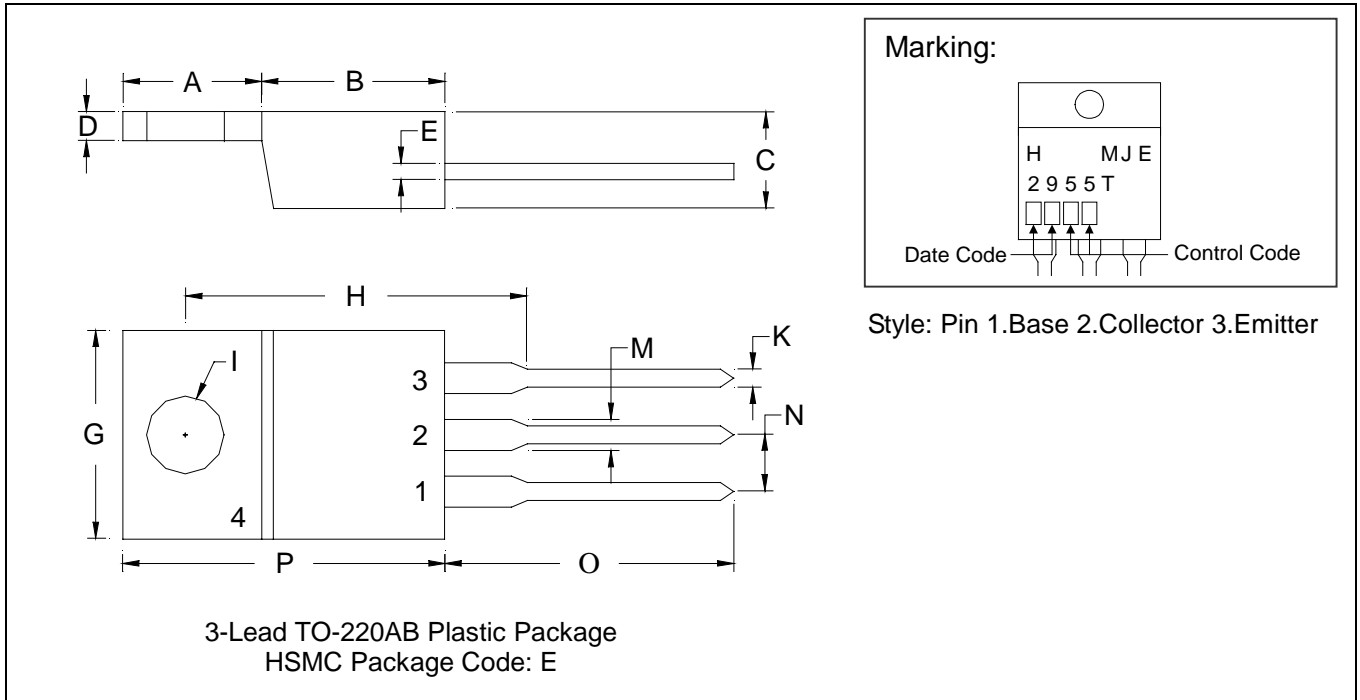
### Characteristics Curve







### TO-220AB Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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